

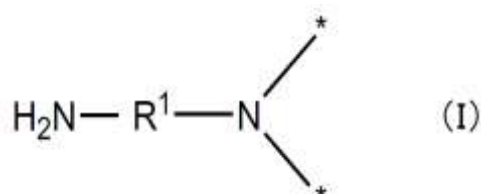
CLAIMS

[1] A method for producing an aluminum platter, the method comprising the following steps 1 and 2:

step 1: bringing a composition into contact with a substrate surface of a Ni-P plated aluminum alloy substrate after one hour or more has elapsed from being polished; and

step 2: forming a magnetic layer on the substrate obtained in the step 1, wherein the step 1 is performed immediately before the step 2, and

the composition consists of a compound (component A) that has at least one structure represented by the following formula (I) and has a molecular weight between 50 and 100,000 inclusive, a chelating agent (component B), water (component C), and an alkali agent (component D) other than the component A,



where, in the formula (I), R¹ is at least one selected from an ethylene group, a propylene group, and an isopropylene group, and * represents a bond.

[2] The method for producing an aluminum platter according to claim 1, wherein the step 1 is a step of bringing the composition into contact with the substrate, rinsing the substrate with an aqueous solvent, and drying the substrate.

[3] The method for producing an aluminum platter according to claim 1 or 2, wherein the composition is an aqueous solution.

[4] The method for producing an aluminum platter according to any one of claims 1 to 3,

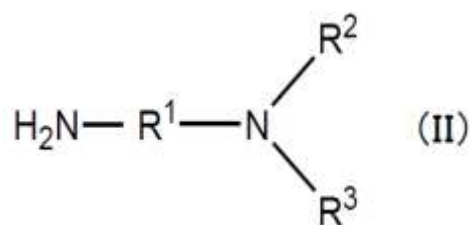
wherein the Ni-P plated aluminum alloy substrate has a diminished smoothness as compared with that immediately after being polished.

[5] The method for producing an aluminum platter according to any one of claims 1 to 4,

wherein the composition is a smoothing agent composition for smoothing a surface of the substrate on which a magnetic layer is to be formed.

[6] The method for producing an aluminum platter according to any one of claims 1 to 5,

wherein the component A is at least one selected from a compound represented by the following formula (II) and polyethyleneimine,



where, in the formula (II), R¹ is at least one selected from an ethylene group, a propylene group, and an isopropylene group, and R² and R³ are each independently at least one selected from a hydrogen atom, a methyl group, an ethyl group, a hydroxymethyl group, a hydroxyethyl group, a hydroxypropyl group, an aminoethyl group, an aminopropyl group, and a $-(\text{CH}_2)_2\text{NH}(\text{CH}_2)_2\text{NH}_2$ group.

[7] The method for producing an aluminum platter according to any one of claims 1 to 6,

wherein a pH of the composition is between 9 and 14 inclusive.

[8] The method for producing an aluminum platter according to any one of claims 1 to 7,

wherein a pH of the composition is between 11.8 and 14 inclusive.

[9] The method for producing an aluminum platter according to any one of claims 1 to 8,

wherein the composition is substantially free of at least one selected from a

compound having an aromatic sulfonic acid group, an anionic surfactant, a nonionic surfactant, and an abrasive.

[10] The method for producing an aluminum platter according to any one of claims 1 to 9,

wherein the component B is at least one selected from the group consisting of gluconic acid, ethylenediaminetetraacetic acid, diethylenetriaminepentaacetic acid, 1-hydroxyethylidene-1,1-diphosphonic acid, thioglycolic acid, glycine, and salts thereof.

[11] The method for producing an aluminum platter according to any one of claims 1 to 10,

wherein the substrate in the step 1 has an oxidized substrate surface.

[12] The method for producing an aluminum platter according to any one of claims 1 to 11,

wherein the step 1 and the step 2 are performed continuously in this order.